

LTM4625 25LD -BGA-PBF 6.25mmX6.25mmX5.01mm (TABLE OF MATERIAL DECLARATION)

The LTM4625 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.0482	Barium Compounds	7727-43-7	0.00097	2.01
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2 non-disclosure	0.01320	27.41
				Copper Metal	7440-50-8	0.02061	42.78
				Copper Compounds	147-14-8	0.00001	0.02
				Ecotoxig substances	7440-38-2 7440-28-0	0.00000	0.01
				Gold metal or alloy	7440-57-5	0.00009	0.18
				Nickel	7440-02-0	0.00067	1.40
				Zinc	7440-66-6	0.00004	0.08
				Continuous Filament Fiber Glass	65997-17-3	0.01038	21.54
				Acrylic Resin	non-disclosure	0.00184	3.82
				Expoxy Resin	non-disclosure	0.00003	0.06
				Chromium (III) oxide	1308-38-9	0.00000	0.00
				Silica amorphous	7631-86-9	0.00005	0.10
				Talcinot containing fibers like asbestos	14807-96-6	0.00011	0.23
				Aromatic carbonyl compounds	non-disclosure	0.00011	0.22
				Cyanoguanidine	461-58-5	0.00000	0.01
				Calcium Caobonate	471-34-1	0.00001	0.01
				Amine compounds	non-disclosure	0.00002	0.03
				Leveling agent and others	non-disclosure	0.00004	0.09
				2	Solder Paste	Alloy	0.0787
Sb	7440-36-0	0.00394	5.00				
3	Passive/Active Components		0.1814	Iron Powder (Fe)	7439-89-6	0.14215	78.36
				Copper (Cu)	7440-50-8	0.03489	19.23
				Nickel (Ni)	7440-02-0	0.00054	0.30
				Tin (Sn)	7440-31-5	0.00120	0.66
				Ceramic (Ba) Compounds	12047-27-7	0.00262	1.44
4	Active lcs	Silicon	0.0016	Silicon	7440-21-3	0.00161	100.00
5	Wire	Gold	0.0031	Au	7440-57-5	0.00314	99.99
6	Solder Ball	SAC305	0.0540	Sn	7440-31-5	0.05207	96.50
				Ag	7440-22-4	0.00162	3.00
				Cu	7440-50-8	0.00027	0.50
7	Encapsulation	Epoxy Resin	0.1609	Fused Silica	60676-86-0	0.12421	77.20
				Epoxy Resin	non-disclosure	0.01432	8.90
				Phenol Resin	non-disclosure	0.01432	8.90
				Crytalline Silica	14808-60-7	0.00483	3.00
				Carbon Black	1333-86-4	0.00080	0.50
				Metal Hydroxide	non-disclosure	0.00241	1.50
Total Package Weight			0.5279				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts